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 Cher Ming Tan; Zhenghao Gan; Xiaofang Gao;
 Semiconductor Manufacturing, IEEE Transactions on
 Volume 16, Issue 2, May 2003 Page(s):314 - 318
 Digital Object Identifier 10.1109/TSM.2003.811886
[AbstractPlus](#) | [References](#) | Full Text: [PDF](#)(354 KB) IEEE JNL
- ☐ 2. **Thermal transient modeling and experimental validation in the European**
 Pape, H.; Schweitzer, D.; Janssen, J.H.J.; Morelli, A.; Villa, C.M.;
 Components and Packaging Technologies, IEEE Transactions on [see also Cc
 Packaging and Manufacturing Technology, Part A: Packaging Technologies, IE
 on]
 Volume 27, Issue 3, Sept. 2004 Page(s):530 - 538
 Digital Object Identifier 10.1109/TCAPT.2004.831791
[AbstractPlus](#) | [References](#) | Full Text: [PDF](#)(1040 KB) IEEE JNL
- ☐ 3. **Crystal SiGeC far infrared sensor with temperature isolation improvemen**
 Ming-Chun Hsieh; Yean-Kuen Fang; Pei-Ming Wu; Wen-De Wang;
 Electronics Letters
 Volume 39, Issue 8, 17 April 2003 Page(s):656 - 658
 Digital Object Identifier 10.1049/el:20030442
[AbstractPlus](#) | Full Text: [PDF](#)(344 KB) IEE JNL
- ☐ 4. **Anodic bonding of optical fibers to silicon for integrating MEMS based op**
and temperature sensors onto optical fibers
 Saran, A.; Abeysinghe, D.C.; Deshmukh, P.; Flenniken, R.; Boyd, J.T.;
 TRANSDUCERS, Solid-State Sensors, Actuators and Microsystems, 12th Inter
 Conference on, 2003
 Volume 1, 8-12 June 2003 Page(s):564 - 567 vol.1
[AbstractPlus](#) | Full Text: [PDF](#)(363 KB) IEEE CNF
- ☐ 5. **Predicting hysteretic oscillations in over-temperature protection of a pow**
transient electrothermal circuit simulation
 Williams, R.K.; Sevilla, L.T.; Rodamaker, M.C.;
 Power Semiconductor Devices and ICs, 1993. ISPSD '93. Proceedings of the
 Symposium on
 18-20 May 1993 Page(s):304 - 309
 Digital Object Identifier 10.1109/ISPSD.1993.297143

13. Double-Sided IPEM Cooling Using Miniature Heat Pipes

Martens T. J. ; Nellis G. F. ; Pfotenhauer J. M. ; Jahns T. M. ;

IEEE Transactions on Components and Packaging Technologies : Accepted for publication

Volume PP, Issue 99, 2005 Page(s):1 - 10

Digital Object Identifier 10.1109/TCAPT.2005.848591

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